

SUBMINIATURE SOLID STATE LAMP

Part Number: AM27SGC09 Super Bright Green

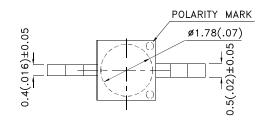
Features

- Subminiature package.
- Z-Bend lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

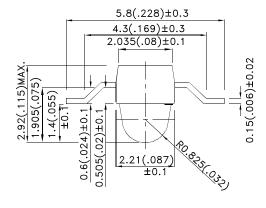
Description

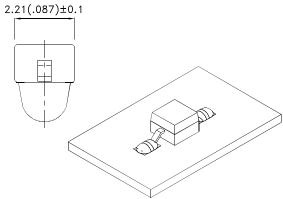
The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions









Notes:

- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM27SGC09	Super Bright Green (GaP)	Water Clear	50	100	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA
lR	Reverse Current	Super Bright Green		10	uA	V _R =5V

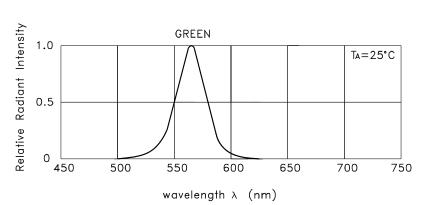
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units	
Power dissipation	62.5	mW	
DC Forward Current	25	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

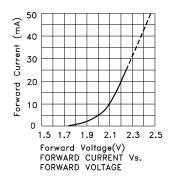
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

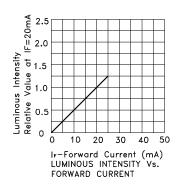
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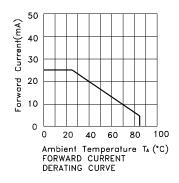


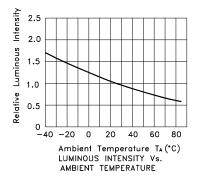
RELATIVE INTENSITY Vs. WAVELENGTH

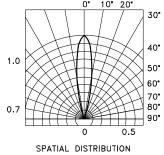
Super Bright Green AM27SGC09











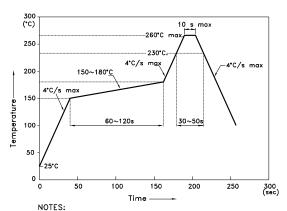
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



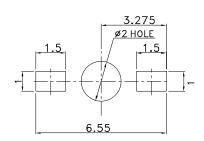
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

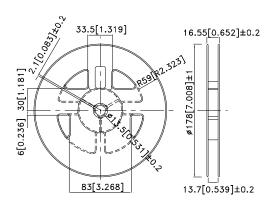
 3.Number of reflow process shall be 2 times or less.

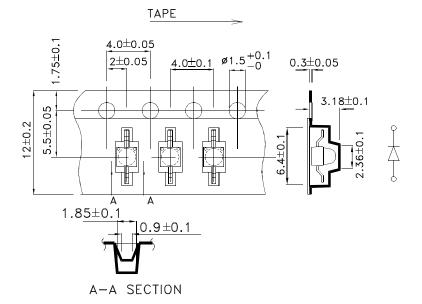
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

Reel Dimension

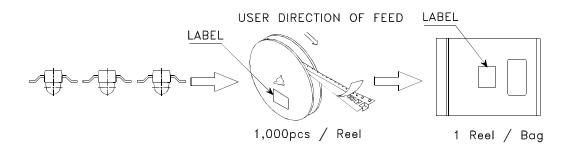


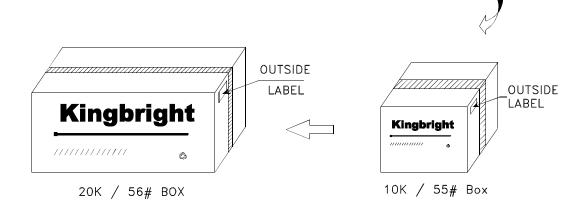


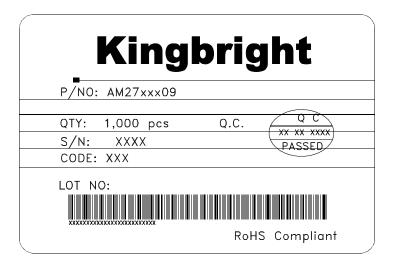
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PACKING & LABEL SPECIFICATIONS

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